Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. – 25. (Canceled).

26. (Currently Amended) A system comprising:

an enclosure having a chassis therein and adapted to operatively house heat-producing electronic equipment and defining an air flow path into the enclosure, across the electronic equipment and out of the enclosure;

~~an air mover coupled to the chassis to induce a flow of air along a flow path within the chassis;~~

~~a first electronics compartment positioned in the chassis and in the air flow path;~~

a first ~~air-to-fluid~~ heat exchanger positioned in the enclosure ~~chassis~~ and in the air flow path, and comprising a plurality of cooling fins, each having a fluid passage therein ~~wherein the first heat exchanger includes at least one internal fluid passage configured to carry a working fluid at least a portion of which undergoes a phase change within the at least one fluid passage to absorb heat from the air flow path~~;

a working fluid configured to change state from a first phase to a second phase within at least one of the fluid passages in response to heat in the air flow path;

a heat exchanger positioned ~~external~~ externally to and spaced apart from the ~~chassis~~ enclosure and in fluid communication with the first heat exchanger, wherein the external heat exchanger is configured to change the state of ~~cool~~ the working fluid from the second phase to the first phase;

a pump located downstream of the external heat exchanger and configured to circulate the working fluid in the first phase to the first heat exchanger; and

a controller operably coupled to the system and configured to control the ~~pressure or~~ temperature of the working fluid supplied to the first heat exchanger above a dew point of the air in the air flow path ~~to facilitate phase change of the working fluid within the first heat exchanger~~.

27. (Currently Amended) The system of claim 26, ~~further comprising the working fluid,~~ wherein the working fluid has a boiling point in the first heat exchanger between about 45° F. and about 75° F.

28. (Currently Amended) The system of claim 26, further comprising a plurality of computer modules held in [[the]] a first electronics compartment.

29. (Currently Amended) The system of claim 28 ~~claim 26~~, further comprising a second electronics compartment positioned in the chassis and in the air flow path wherein the first heat exchanger is positioned at least partially between the first and second electronics compartments.

30. (Canceled).

31. (Canceled).

32. (Currently Amended) The system of claim 26 wherein the chassis is partitioned into a plurality of ~~first~~ electronics compartments ~~compartment~~ and each is configured to hold a plurality of computer modules oriented edgewise with respect to the air flow path.

33. (Currently Amended) The system of claim 32 ~~claim 26, wherein the chassis has an air inlet and an air outlet; and~~ further comprising:

an air mover associated with the enclosure;

a first plurality of computer modules held in [[the]] a first electronics compartment at least partially in the air flow path;

a second electronics compartment positioned in the air flow path in the chassis and spaced apart from the first electronics compartment;

a second plurality of computer modules held in the second electronics compartment at least partially in the air flow path; and

a second air-to-fluid heat exchanger positioned in the air flow path in the chassis, wherein the second heat exchanger is positioned at least partially downstream of the first electronics compartment and at least partially upstream of the second electronics compartment, and wherein the second heat exchanger includes at least one opening through which the air mover moves air to transfer heat from the air to the fluid.

34. (Previously Presented) The system of claim 33 wherein the air mover is positioned toward an upper portion of the chassis and configured to draw air upward through the chassis and past the first electronics compartment, the first and second heat exchanger, and the second electronics compartment.

35. (Withdrawn – Previously presented) The system of claim 33 wherein the air mover is positioned toward a bottom portion of the chassis and configured to drive air through the chassis and past the first electronics compartment, the heat exchanger, and the second electronics compartment.

36. (Previously presented) The system of claim 33 wherein the air mover is carried by the chassis.

37. (Previously presented) The system of claim 33 further comprising:

a third electronics compartment positioned in the air flow path in the chassis and spaced apart from the second electronics compartment;

a third plurality of computer modules held in the third electronics compartment at least partially in the air flow path; and

a third heat exchanger positioned in the air flow path in the chassis, wherein the third heat exchanger is positioned at least partially downstream of the second electronics compartment and at least partially upstream of the third electronics compartment, and wherein the third heat exchanger includes at least one opening through which the air mover moves air.

38. (Previously presented) The system of claim 33 wherein the air mover, the electronics compartments, and the heat exchangers are arranged vertically with respect to the chassis.

39. (Previously presented) The system of claim 33 wherein the first electronics compartment is configured to hold the first plurality of computer modules in edgewise orientation with respect to the air flow path toward a first side of the first heat exchanger, and wherein the second electronics compartment is configured to hold the second plurality of computer modules in an edgewise orientation with respect to the air flow path from a second side of the first heat exchanger opposite to the first side of the first heat exchanger.

40. (Previously presented) The system of claim 33 wherein each of the first plurality of computer modules is individually carried by the first electronics compartment, wherein each of the first plurality of computer modules includes at least a first computer processor, wherein each of the second plurality of computer modules is individually carried by the second electronics compartment, and wherein each of the second plurality of computer modules includes at least a second computer processor.

41. (Canceled).

42. (Previously presented) The system of claim 33 wherein working fluid has a boiling point in the heat exchangers between about 45° F. and about 75° F.

43. (Previously presented) The system of claim 33 wherein each computer module of the first and second pluralities of computer modules includes at least one processor.

44. – 74. (Canceled).

75. (Previously presented) The system of claim 26, wherein a control strategy of the controller is selected from the group consisting of: controlling the static pressure of the working fluid; subcooling the working fluid; increasing the heat transfer capacity of the external heat exchanger; and any combination thereof.

76. – 78. (Canceled).

79. (Currently Amended) A method for cooling an electronic component housed in a cabinet, comprising:

providing the cabinet with an air inlet and an air outlet defining an air flow path therebetween;

locating an air-to-fluid heat exchanger within the cabinet and within the air flow path;

providing a heat exchanger external to and spaced from the cabinet;

locating a working fluid pump between the air-to-fluid heat exchanger and the external heat exchanger and downstream of the external heat exchanger;

circulating a working fluid through the air-to-fluid heat exchanger and the external heat exchanger, the working fluid configured to change state from a first phase to a second phase within the air-to-fluid heat exchanger;

changing the state of at least a portion of the working fluid from the first phase to the second phase in the air-to-fluid heat exchanger in response to heat in the air flow path;

~~moving air through the air inlet, into the cabinet, across the electronic component and through the air-to-fluid heat exchanger to transfer heat from the electronic component to the working fluid~~;

removing heat from the working fluid in the external heat exchanger;

changing the state of the working fluid from the second phase to the first phase in the external heat exchanger in response to removing heat therefrom; and

controlling the heat removal so that a temperature of the working fluid circulated to ~~at least a portion of the working fluid changes state within~~ the air-to-fluid heat exchanger is above a dew point of the air in the air flow path.

80. (Previously presented) The method of claim 79, wherein controlling the working fluid does not cause the temperature of the air-to-fluid heat exchanger to drop below the dew point.

81. (Previously presented) The method of claim 79, wherein controlling the working fluid does not cause condensation to form on the air-to-fluid heat exchanger or on the electronic component.

82. (Previously presented) The method of claim 79, wherein controlling the working fluid includes controlling the static pressure of the working fluid or subcooling the working fluid or increasing the condensing capacity of the external heat exchanger.

83. (Currently Amended) The method of claim 79, wherein the external heat exchanger is a fluid-to-fluid heat exchanger and ~~the second working fluid~~ is cooled with chilled water.

84. (Previously presented) The method of claim 79, further comprising a plurality of electronic components and a plurality of air-to-fluid heat exchangers.